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Title: Semiconductor Package with Integrated Heat Spreader Attached to a  
Thermally Conductive Substrate Core  
Inventor(s): Timothy M. Takeuchi  
Atty. Docket No.: 42390P13557

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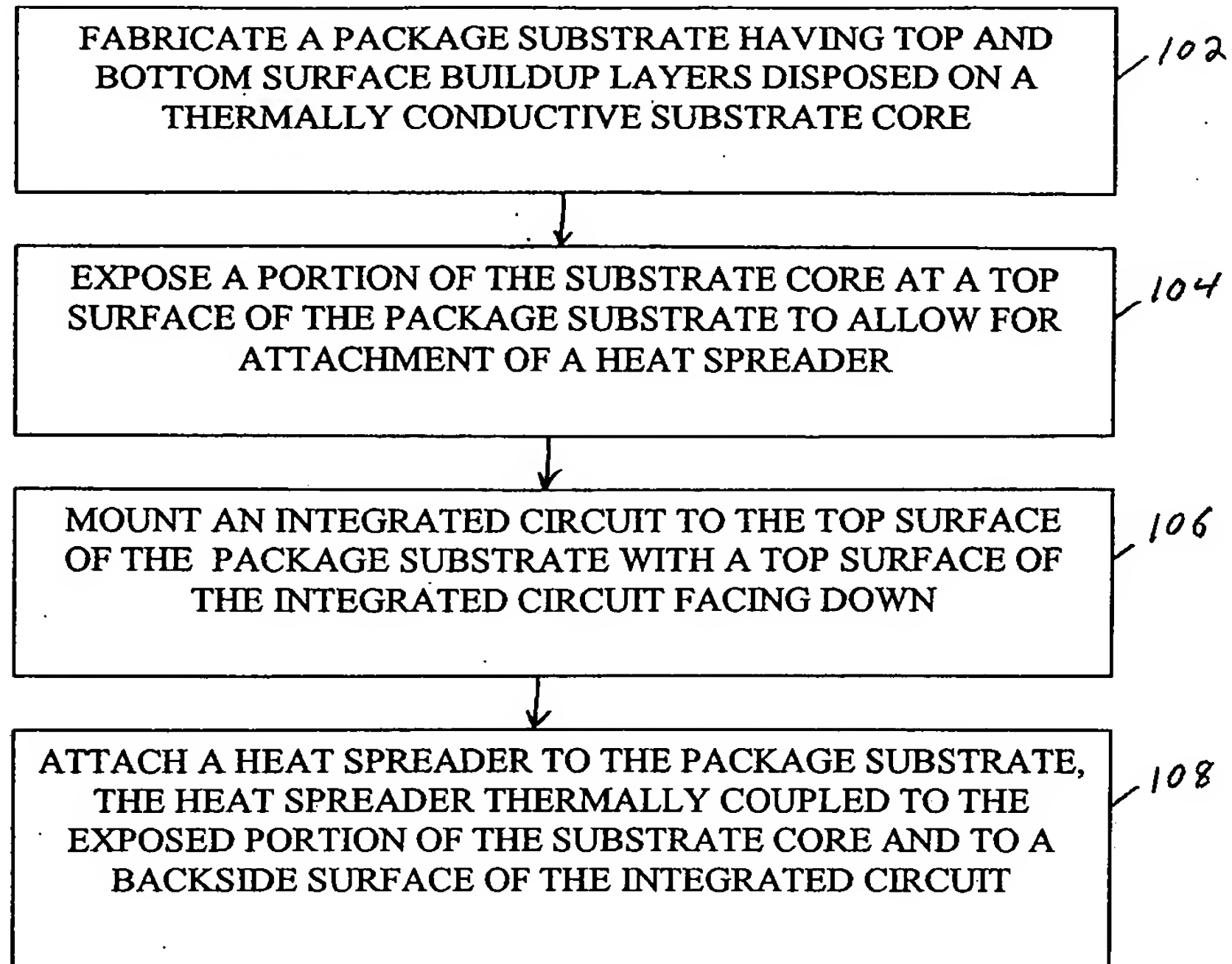


Figure 1

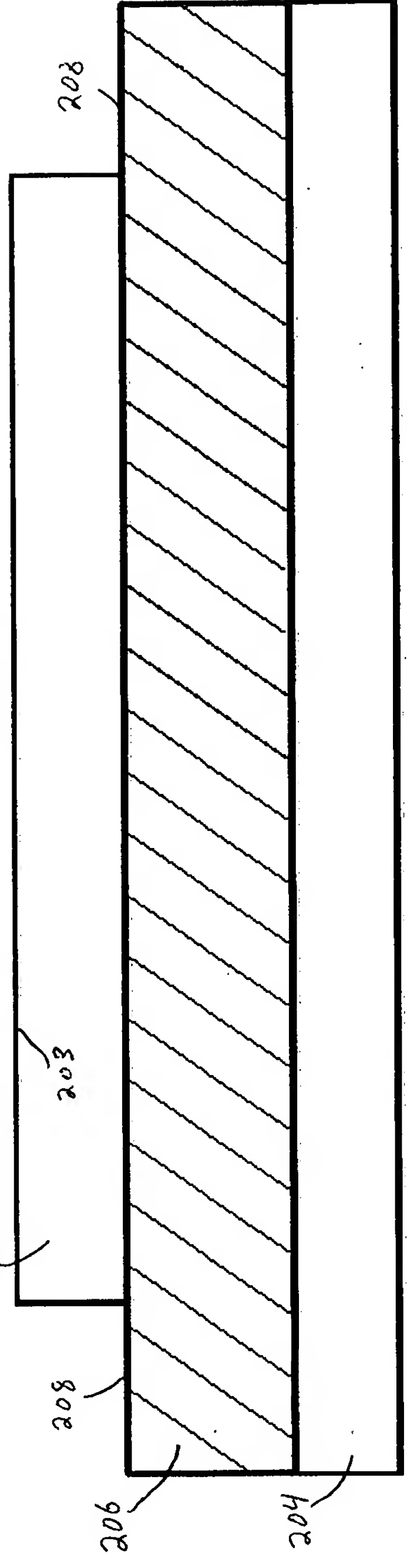


Figure 2

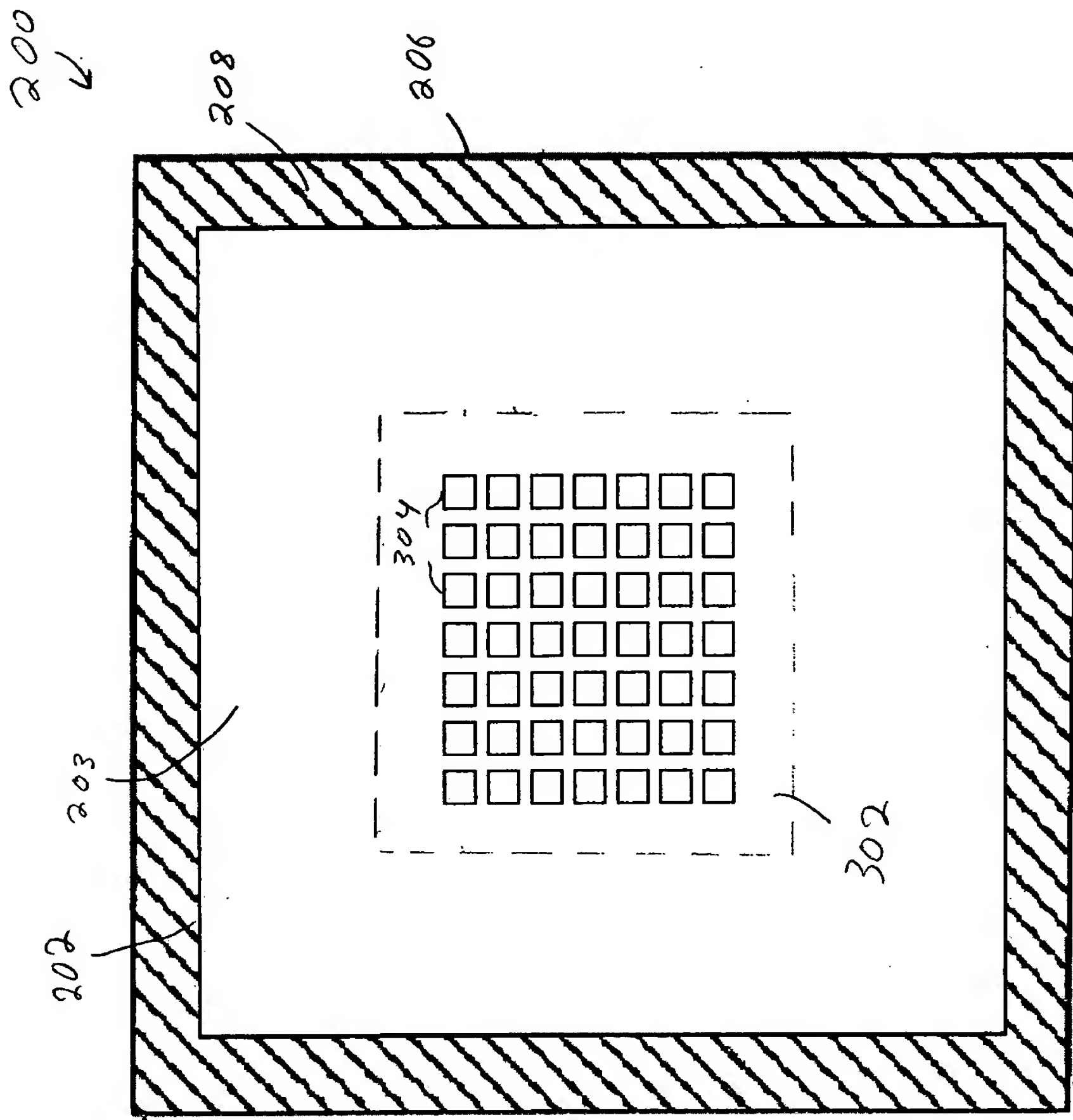


Figure 3

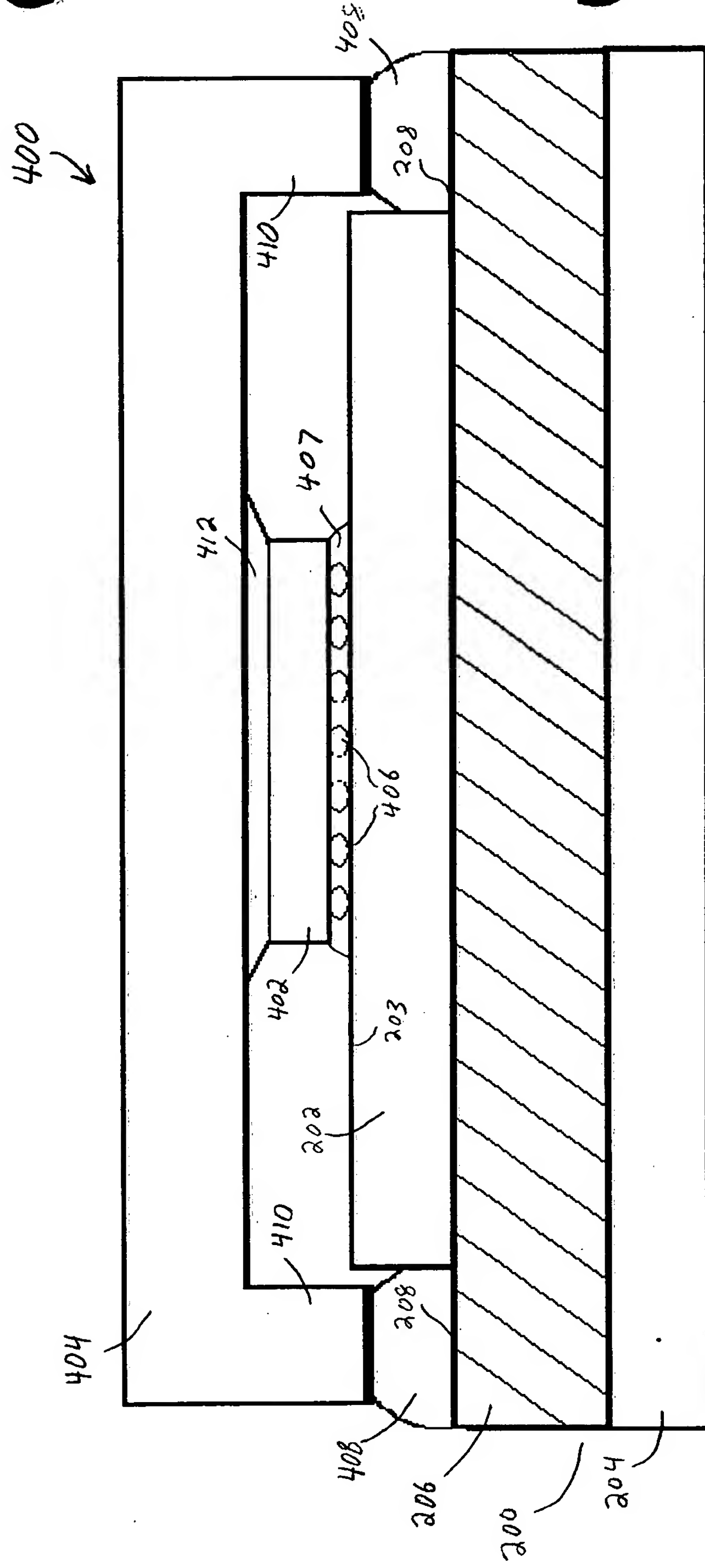


Figure 4

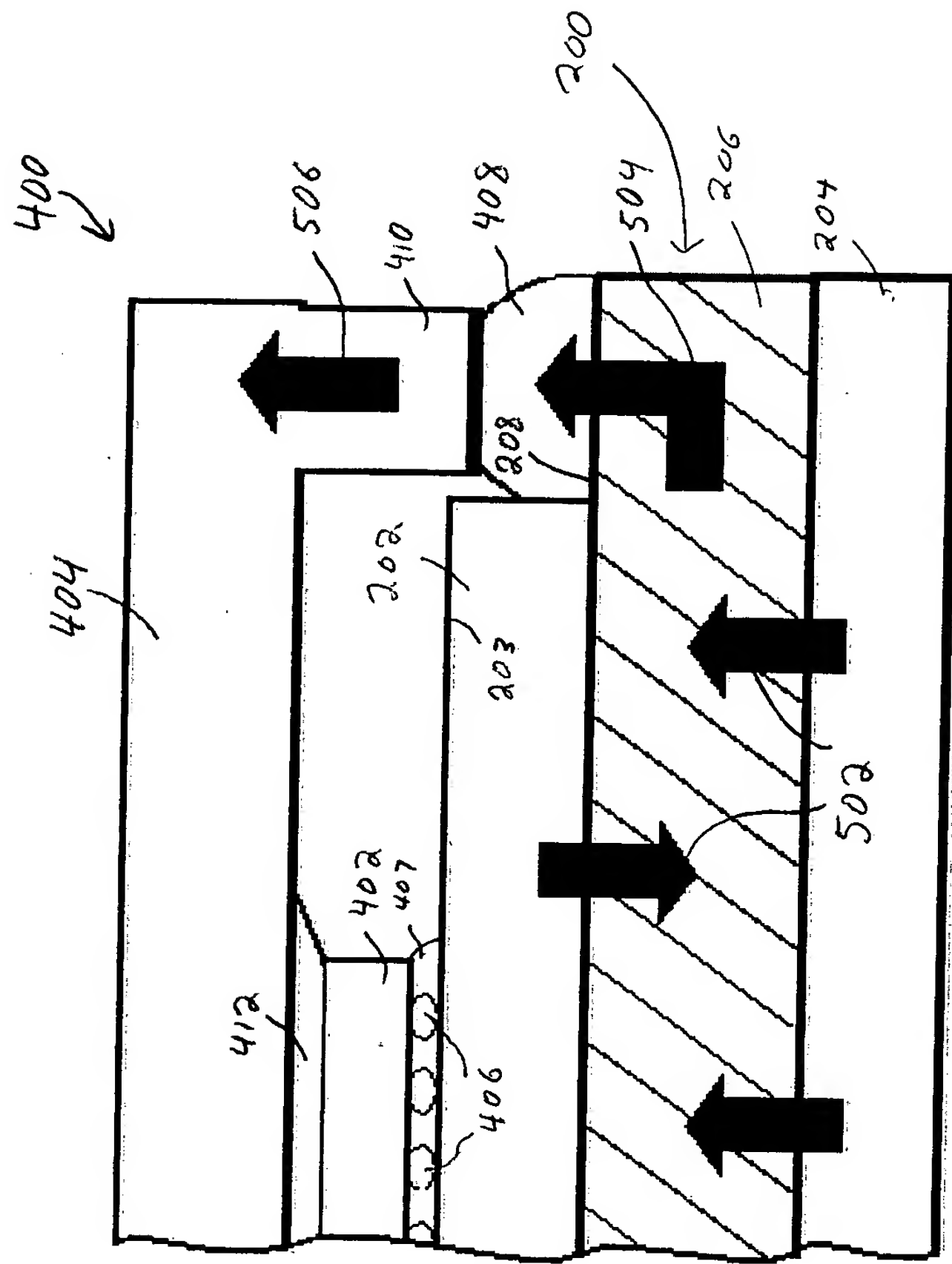


Figure 5

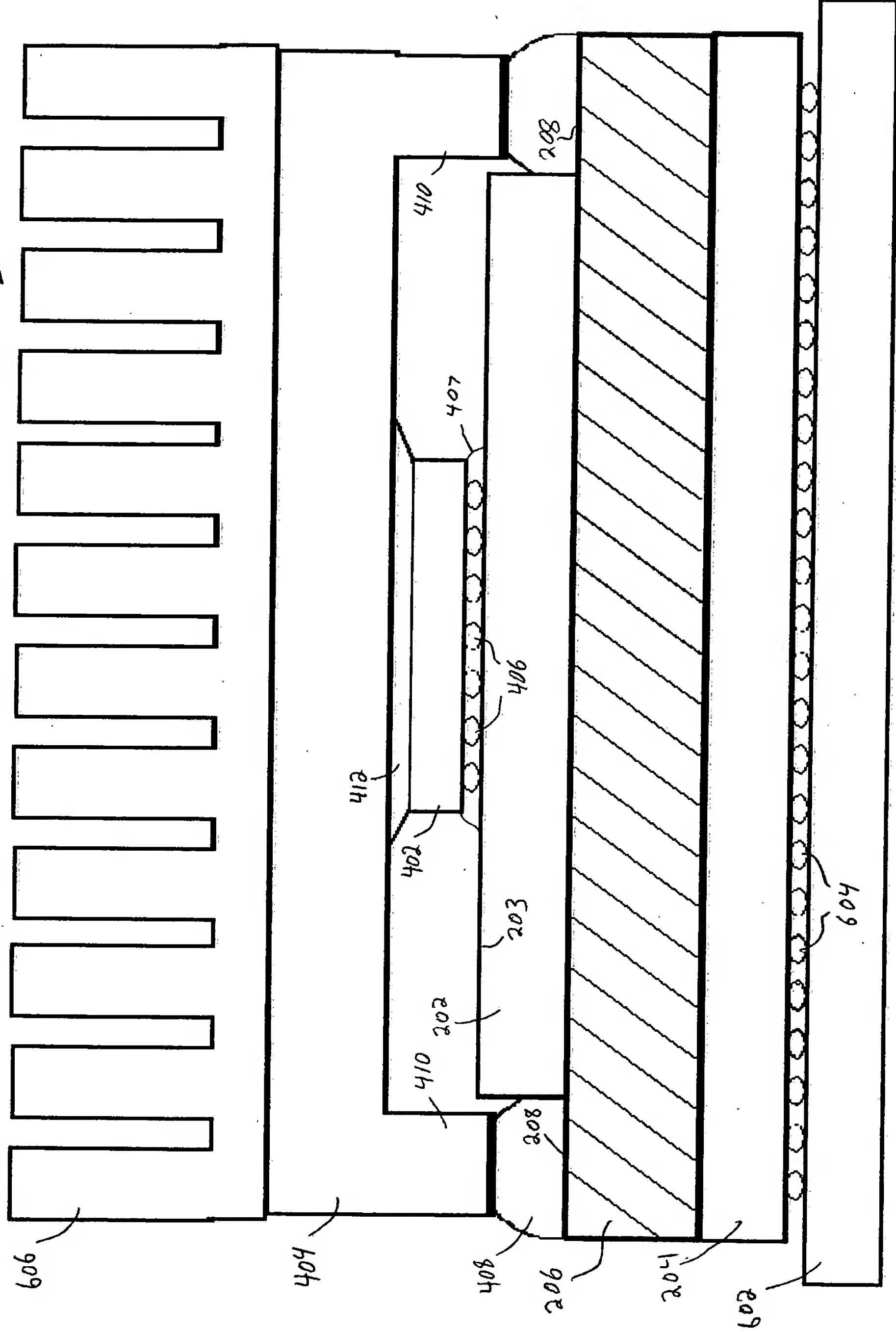


Figure 6

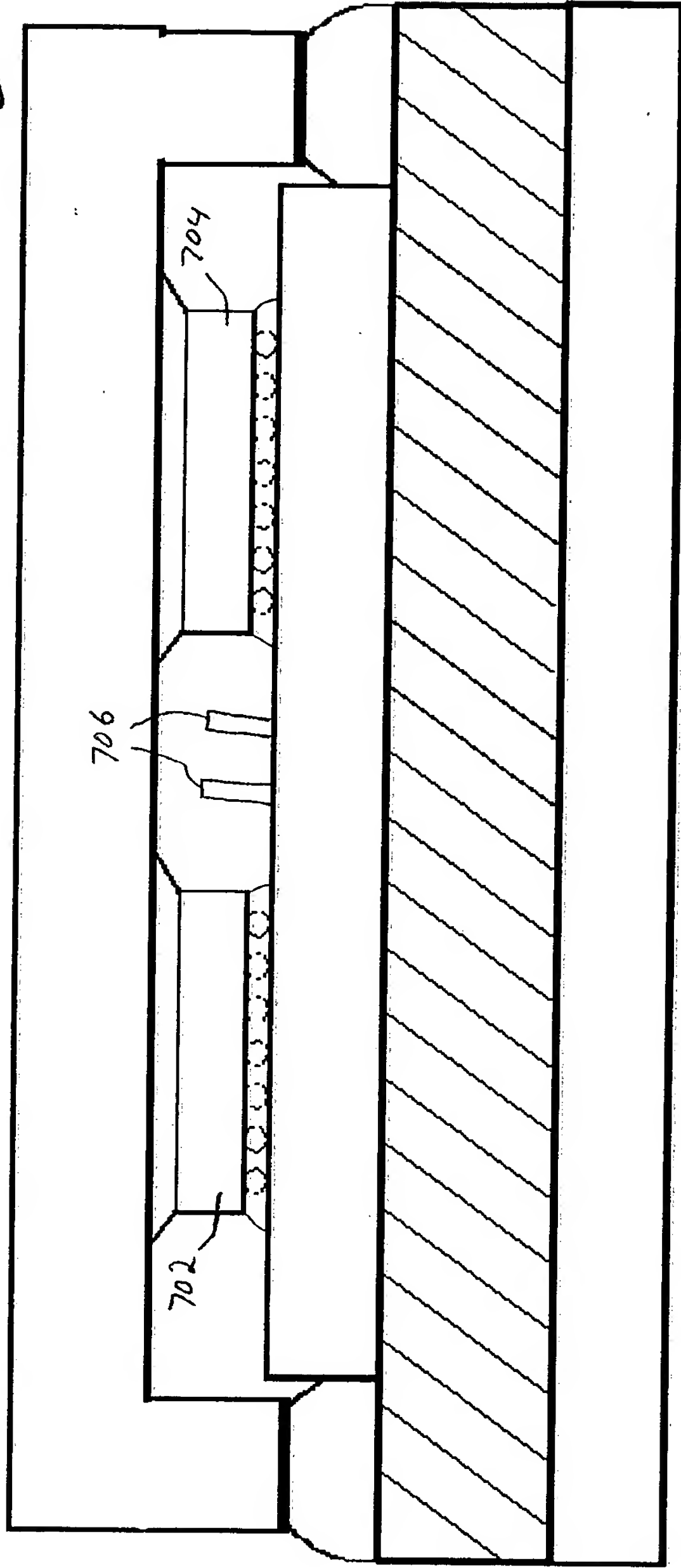


Figure 7